nRF54LM20B-PAAA Reference Package Changelog

Date: 2026-11-19

8 Layers

Config 1

rev 0.6 → 1.0 (2026-11-19)

- Editorial updates to schematic and layout documents
- nRF54LM20B PAAA footprint aligned with mechanical specification in datasheet
  - BGA ball pattern offset by 0.09 mm from the component body center
- Renumbering of designators for decoupling and RF matching components relative to v0.6 release.
  - C4, C5, C1, C2, C6, C7, C14, C3, C12, C13, C10, C11, C8 renumbered to C1-C13 respectively with values unchanged
  - L1, L2, L3, L4 renumbered to L4, L1, L2 and L3 respectively with values unchanged

rev 0.5 → 0.6

- FB2 removed
- C12 updated to 1.5pF
- L4 changed to 3.3nH
- C6 changed to 4.7µF
- C7 changed to N.C.
- X2 changed to X1
- X1 changed to X2

rev 0.4 → 0.5

- Pad D1 on nRF54LM20 connected to GND on top layer
- Removed thermal relief on C3, C12 and C13

rev 0.3 → 0.4

- C9 removed
- L5 and C8 added
- L2 changed to 3.6nH
- L3 changed to 4.7nH
- L4 changed to 2.2nH
- C3 and C12 changed to 1.2pF
- C13 changed to DNM
- C6 changed to 4.7µF
- R2 changed to 200ohm
- Updated component placement on C8, C14, L5 ,FB2 and X2 to match the schematic
- Removed GND on inner layers below the 50 ohm impedance trace

rev 0.3

- First release